8A1 21

8A2 22

9A1 23

9A2 🛛 24

28 8B1

26 9B1

25 🛛 9B2

27 8B2

SCDS0060 - NOVEMBER 1992 - REVISED NOVEMBER 2004

 Members of the Texas Instruments Widebus™ Family 5-Ω Switch Connection Between Two Ports TTL-Compatible Input Levels 	SN54CBT16209 WD PACKAGE SN74CBT16209A DGG, DGV, OR DL PACKAGE (TOP VIEW) S0 $\begin{bmatrix} 1 & 48 \end{bmatrix}$ S1
description (and aring information	1A1 [] 2 47 [] S2
description/ordering information	1A2 🛛 3 46 🛛 1B1
The SN54CBT16209 and SN74CBT16209A	GND 🛛 4 45 📮 1B2
	2A1 🛛 5 44 🗍 2B1
devices provide 18 bits of high-speed	2A2 🛛 6 43 🗍 2B2
TTL-compatible bus switching or exchanging. The low on-state resistance of the switches allows	V _{CC} [] 7 42] GND
	3A1 🛛 8 41 🖸 3B1
connections to be made with minimal propagation delay.	3A2 🛛 9 40 🖸 3B2
delay.	GND 🛛 10 39 🗍 GND
The devices operate as an 18-bit bus switch or a	4A1 🛛 11 🛛 38 🗍 4B1
9-bit bus exchanger, which provides data	4A2 🛛 12 37 🕽 4B2
exchanging between the four signal ports via the	5A1 🛛 13 36 🗍 5B1
data-select (S0, S1, S2) terminals.	5A2 🛛 14 35 🗍 5B2
	GND 🛛 15 34 🗍 GND
	6A1 🛛 16 33 🗍 6B1
	6A2 🛛 17 32 🗍 6B2
	7A1 0 18 31 7B1
	7A2 19 30 7B2
	GND 20 29 GND

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP - DL	Tube	SN74CBT16209ADL	
4000 10 0500	550P - DL	Tape and reel	SN74CBT16209ADLR	CBT16209A
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74CBT16209ADGGR	CBT16209A
	TVSOP – DGV	Tape and reel	SN74CBT16209ADGVR	CY209A
–55°C to 125°C	CFP – WD Tube		SNJ54CBT16209WD	SNJ54CBT16209WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



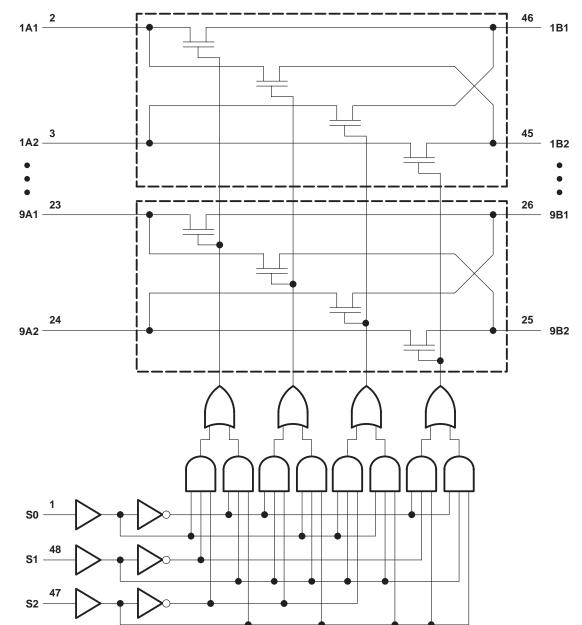
 $Copyright © 2004, \mbox{Texas Instruments Incorporated} \\ On products compliant to MIL-PRF-3853s, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.$

SCDS0060 - NOVEMBER 1992 - REVISED NOVEMBER 2004

	FUNCTION TABLE											
	INPUTS		INPUTS/	OUTPUTS	FUNCTION							
S2	S1	S0	A1	A2	FUNCTION							
L	L	L	Z	Z	Disconnect							
L	L	Н	B1	Z	A1 port = B1 port							
L	Н	L	B2	Z	A1 port = B2 port							
L	Н	Н	Z	B1	A2 port = B1 port							
н	L	L	Z	B2	A2 port = B2 port							
н	L	Н	Z	Z	Disconnect							
н	Н	L	B1	B2	A1 port = B1 port A2 port = B2 port							
н	Н	Н	B2	B1	A1 port = B2 port A2 port = B1 port							



SCDS0060 - NOVEMBER 1992 - REVISED NOVEMBER 2004



logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)		
Continuous channel current		
Input clamp current, I_{IK} (V _I < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2): I	DGG package	70°C/W
	DGV package	58°C/W
	DL package	
Storage temperature range, T _{stg}		5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54CB	Г16209	SN74CBT	16209A	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	4	5.5	V
VIH	High-level control input voltage	2		2		V
VIL	Low-level control input voltage		0.8		0.8	V
Т _А	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR	AMETER		TEST CONDITIONS					
VIK		$V_{CC} = 4.5 V,$	lj = -18 mA				-1.2	V
		$V_{CC} = 0,$	V _I = 5.5 V				10	
1		V _{CC} = 5.5 V,	$V_I = 5.5 \text{ V or GND}$				±1	μA
ICC		V _{CC} = 5.5 V,	I _O = 0,	$V_I = V_{CC}$ or GND			3	μΑ
∆ICC§	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V_{CC} or GND			2.5	mA
Ci	Control inputs	$V_I = 3 V \text{ or } 0$				4		pF
Cio(OFF)		$V_{O} = 3 V \text{ or } 0,$	S0, S1, and S2 = GI	ND		7.5		pF
		$V_{CC} = 4 V$ TYP at $V_{CC} = 4 V$	V _I = 2.4 V,	l _l = 15 mA		14	20	
ron¶			N 0	I _I = 64 mA		4	8	Ω
		$V_{CC} = 4.5 V$	$V_{I} = 0$	lj = 30 mA		4	8	
			V _I = 2.4 V,	l _l = 15 mA		6	15	

[‡] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

¶ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.



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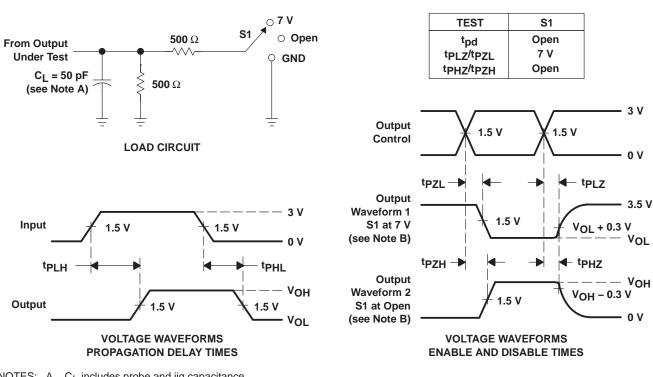
switching characteristics over recommended operating free-air temperature range, CL = 50 pF (unless otherwise noted) (see Figure 1)

			:	SN54CE	ST16209		S	N74CB	T16209A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	= 4 V	= V _{CC} ± 0.	= 5 V 5 V	VCC :	= 4 V	= V _{CC} ± 0.	= 5 V 5 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd} †	A or B	B or A				0.8*		0.35		0.25	ns
^t pd	S	A or B		14	2	13.1		9.9	1.5	9	ns
ten	S	A or B		16	1.7	15.3		10.3	1.5	9.8	ns
^t dis	S	A or B		14.5	1	13.2		9.3	1.5	8.8	ns

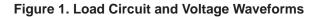
* On products compliant to MIL-PRF-38535, this parameter is not production tested.

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C₁ includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. tPLZ and tPHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tPLH and tPHL are the same as tpd.







6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)				Qty	(2)	(6)	(3)		(4/5)	
SN74CBT16209ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	Samples
SN74CBT16209ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY209A	Samples
SN74CBT16209ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	Samples
SN74CBT16209ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	Samples
SNJ54CBT16209WD	LIFEBUY	CFP	WD	48		TBD	Call TI	Call TI	-55 to 125	5962-9669701QX A SNJ54CBT16209W D	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16209ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74CBT16209ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74CBT16209ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

11-Mar-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16209ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74CBT16209ADGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0
SN74CBT16209ADLR	SSOP	DL	48	1000	367.0	367.0	55.0

MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK

WD (R-GDFP-F**)

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only
 - E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 - GDFP1-F56 and JEDEC MO-146AB



DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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